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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	115
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-2pq208i

Table of Contents

General Description

Device Architecture 1-1
Design Environment 1-7
Summary 1-8
Related Documents 1-8

Detailed Specifications

Operating Conditions 2-1
Thermal Characteristics 2-6
I/O Specifications 2-9
Voltage-Referenced I/O Standards 2-43
Differential Standards 2-50
Module Specifications 2-54
Routing Specifications 2-61
Global Resources 2-66
Axcelerator Clock Management System 2-75
Embedded Memory 2-86
Other Architectural Features 2-106
Programming 2-110

Package Pin Assignments

BG729 3-1
FG256 3-9
FG324 3-16
FG484 3-21
FG676 3-37
FG896 3-52
FG1152 3-71
PQ208 3-84
CQ208 3-89
CQ256 3-94
CQ352 3-98
CG624 3-115

Datasheet Information

List of Changes 4-1
Datasheet Categories 4-7
Safety Critical, Life Support, and High-Reliability Applications Policy 4-7

Figure 1-2 • **Axcelerator Family Interconnect Elements**

Logic Modules

Microsemi's Axcelerator family provides two types of logic modules: the register cell (R-cell) and the combinatorial cell (C-cell). The Axcelerator device can implement more than 4,000 combinatorial functions of up to five inputs (Figure 1-3).

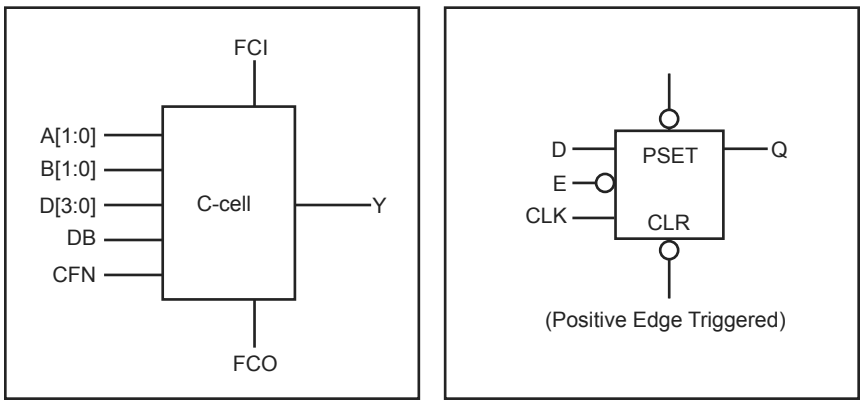


Figure 1-3 • **AX C-Cell and R-Cell**

The R-cell contains a flip-flop featuring asynchronous clear, asynchronous preset, and active-low enable control signals (Figure 1-3). The R-cell registers feature programmable clock polarity selectable on a register-by-register basis. This provides additional flexibility (e.g., easy mapping of dual-data-rate functions into the FPGA) while conserving valuable clock resources. The clock source for the R-cell can be chosen from the hardwired clocks, routed clocks, or internal logic.

Design Environment

The Axcelerator family of FPGAs is fully supported by both Microsemi's Libero® Integrated Design Environment and Designer FPGA Development software. Libero IDE is an integrated design manager that seamlessly integrates design tools while guiding the user through the design flow, managing all design and log files, and passing necessary design data among tools. Additionally, Libero IDE allows users to integrate both schematic and HDL synthesis into a single flow and verify the entire design in a single environment (see the *Libero IDE Flow* diagram located on the Microsemi SoC Products Group website). Libero IDE includes Synplify® Actel Edition (AE) from Synplicity®, ViewDraw® AE from Mentor Graphics®, ModelSim® HDL Simulator from Mentor Graphics, WaveFormer Lite™ AE from SynaptiCAD®, and Designer software from Microsemi.

Designer software is a place-and-route tool and provides a comprehensive suite of backend support tools for FPGA development. The Designer software includes the following:

- Timer – a world-class integrated static timing analyzer and constraints editor which support timing-driven place-and-route
- NetlistViewer – a design netlist schematic viewer
- ChipPlanner – a graphical floorplanner viewer and editor
- SmartPower – allows the designer to quickly estimate the power consumption of a design
- PinEditor – a graphical application for editing pin assignments and I/O attributes
- I/O Attribute Editor – displays all assigned and unassigned I/O macros and their attributes in a spreadsheet format

With the Designer software, a user can lock the design pins before layout while minimally impacting the results of place-and-route. Additionally, Microsemi's back-annotation flow is compatible with all the major simulators and the simulation results can be cross-probed with Silicon Explorer II, Microsemi's integrated verification and logic analysis tool. Another tool included in the Designer software is the SmartGen core generator, which easily creates popular and commonly used logic functions for implementation into your schematic or HDL design.

Designer software is compatible with the most popular FPGA design entry and verification tools from EDA vendors, such as Mentor Graphics, Synplicity, Synopsys, and Cadence Design Systems. The Designer software is available for both the Windows and UNIX operating systems.

Programming

Programming support is provided through Silicon Sculptor II, a single-site programmer driven via a PC-based GUI. In addition, BP Microsystems offers multi-site programmers that provide qualified support for Microsemi devices. Factory programming is available for high-volume production needs.

In-System Diagnostic and Debug Capabilities

The Axcelerator family of FPGAs includes internal probe circuitry, allowing the designer to dynamically observe and analyze any signal inside the FPGA without disturbing normal device operation (Figure 1-9).

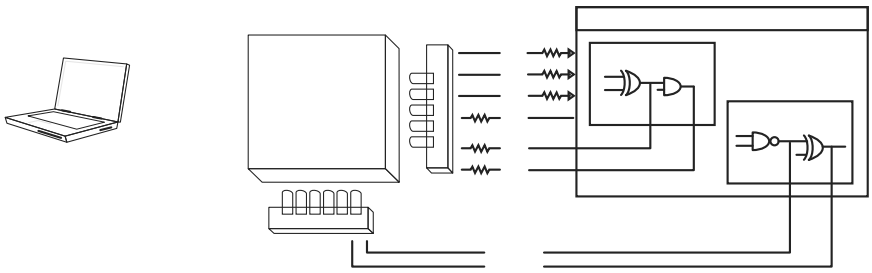


Figure 1-9 • **Probe Setup**

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

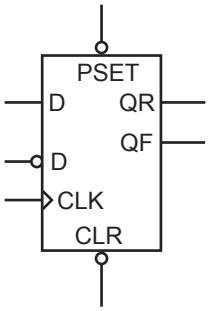


Figure 2-6 • **DDR Register**

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTL standard with slow slew rate and 24 mA-drive strength. LVTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

User I/O Naming Conventions

Due to the complex and flexible nature of the Axcelerator family's user I/Os, a naming scheme is used to show the details of the I/O. The naming scheme explains to which bank an I/O belongs, as well as the pairing and pin polarity for differential I/Os (Figure 2-7).

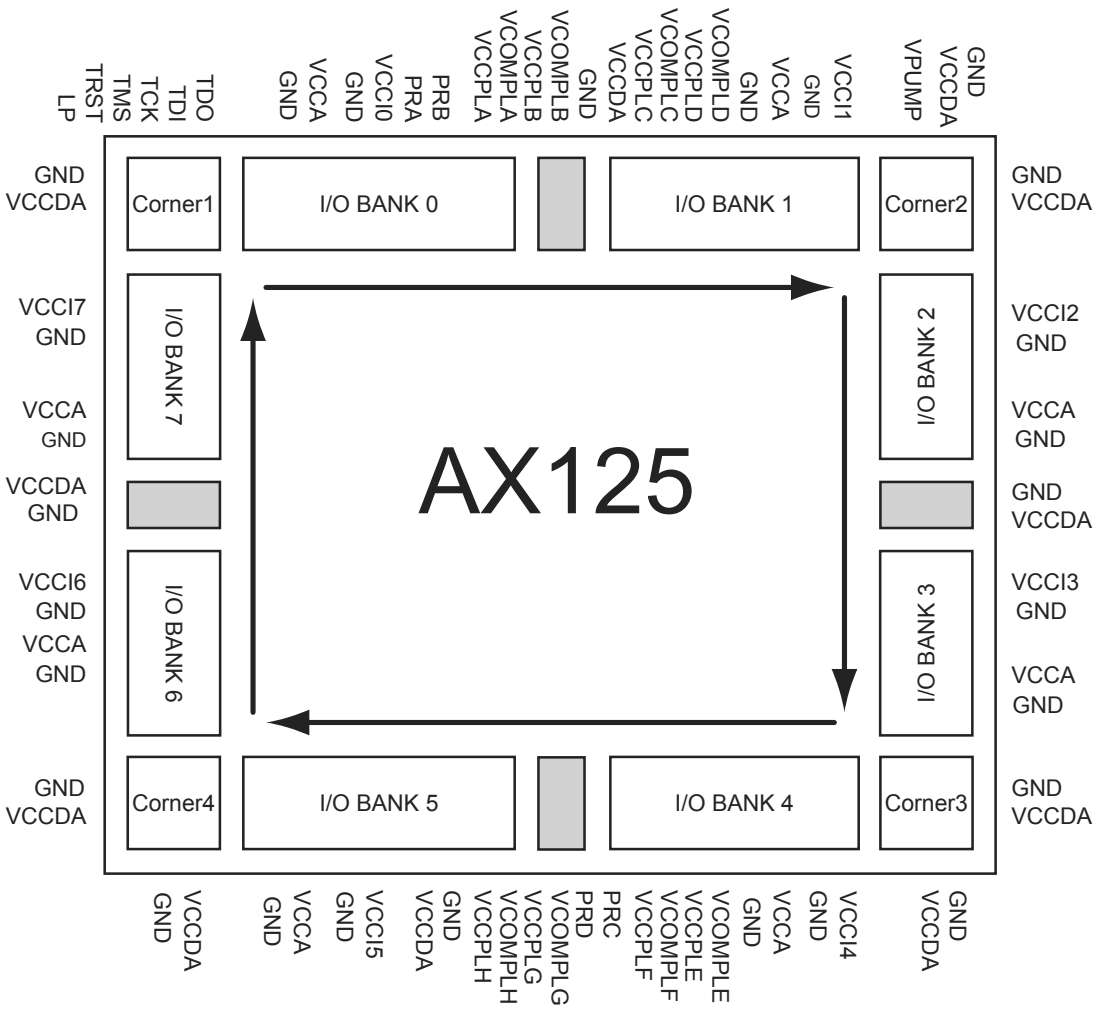
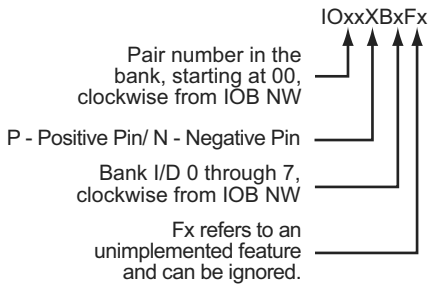


Figure 2-7 • **I/O Bank and Dedicated Pin Layout**



Examples:

IO12PB1F1 is the positive pin of the thirteenth pair of the first I/O bank (IOB NE). IO12PB1 combined with IO12NB1 form a differential pair.

For those I/Os that can be employed either as a user I/O or as a special function, the following nomenclature is used:

IOxxXBxFx/special_function_name

IOxxPB1Fx/xCLKx this pin can be configured as a clock input or as a user I/O.

Figure 2-8 • **General Naming Schemes**

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength =3 (16 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		3.12		3.56		4.18	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.54		4.04		4.75	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.78		3.17		3.72	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.58		2.59		2.60	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Routed Clocks

The routed clock (CLK) is a low-skew network that can drive the clock inputs of all sequential modules in the device (logically equivalent to the HCLK), but has the added flexibility in that it can drive the S0 (Enable), S1, PSET, and CLR input of a register (R-cells and I/O registers) as well as any of the inputs of any C-cell in the device. This allows CLKs to be used not only as clocks, but also for other global signals or high fanout nets. All four CLKs are available everywhere on the chip.

Timing Characteristics

Table 2-75 • **AX125 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t_{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

Table 2-76 • **AX250 Routed Array Clock Networks**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Routed Array Clock Networks								
t_{RCKL}	Input Low to High		2.52		2.87		3.37	ns
t_{RCKH}	Input High to Low		2.59		2.95		3.47	ns
t_{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t_{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t_{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t_{RP}	Minimum Period	1.15		1.31		1.54		ns
t_{RMAX}	Maximum Frequency		870		763		649	MHz

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

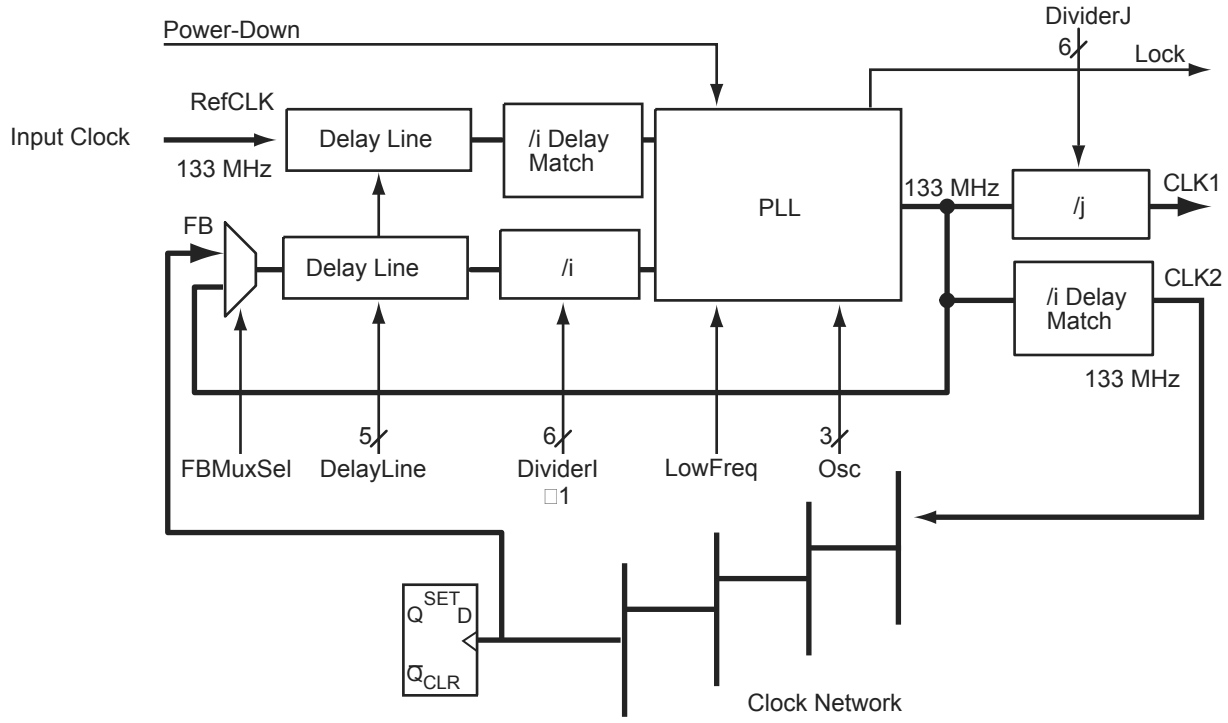


Figure 2-56 • **Using the PLL for Clock Deskewing**

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10µs after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

***Table 2-103* • JTAG Instruction Code**

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

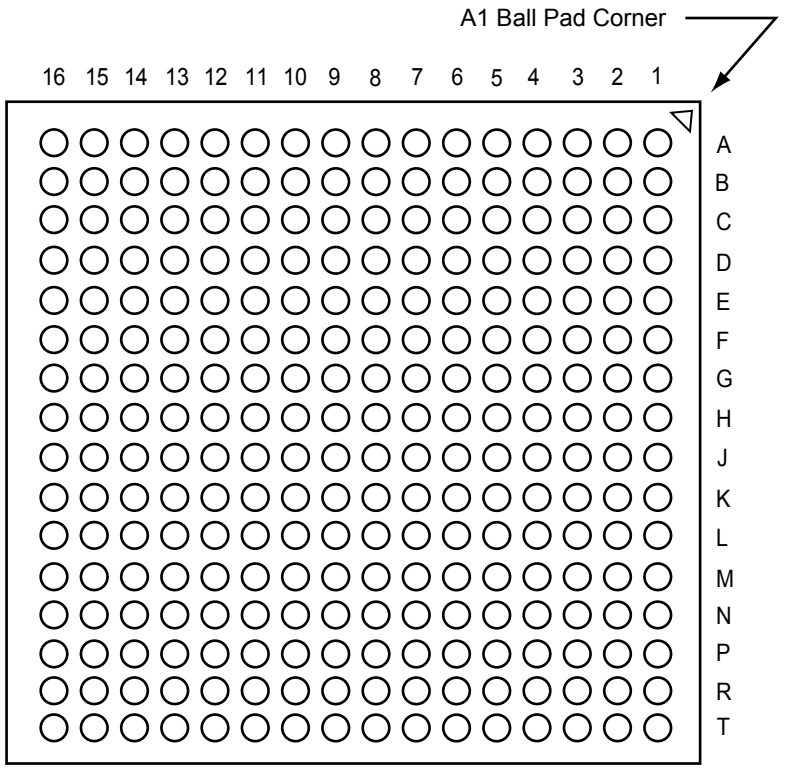
TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 kΩ resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

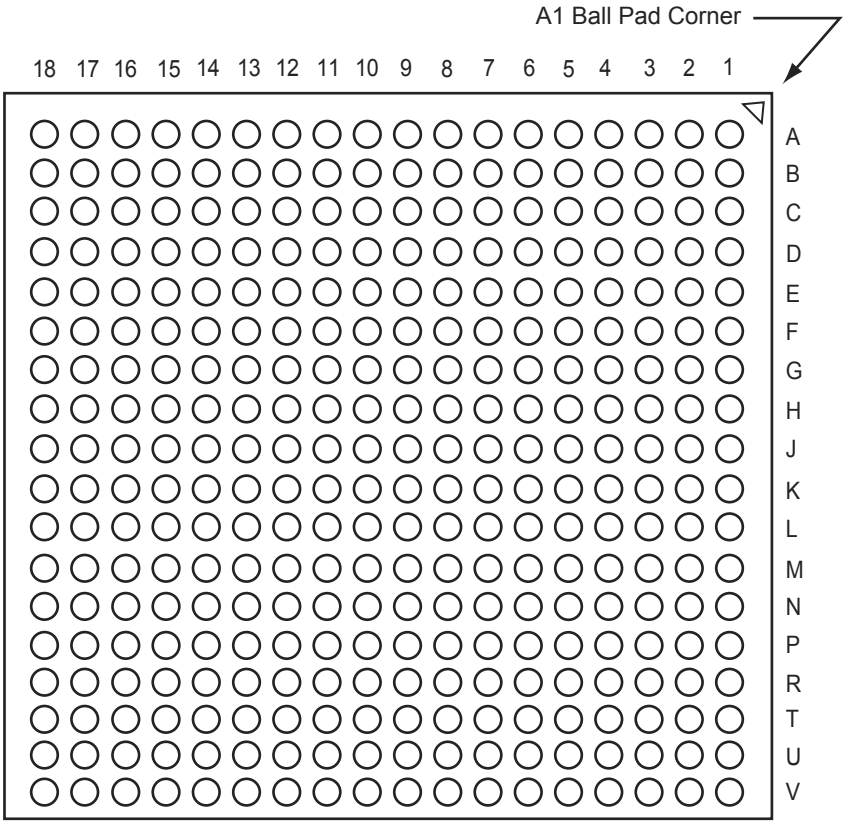
FG256



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG324



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG324	
AX125 Function	**Pin Number**
VCCIB5	N7
VCCIB5	N8
VCCIB5	N9
VCCIB6	K6
VCCIB6	L6
VCCIB6	M6
VCCIB7	G6
VCCIB7	H6
VCCIB7	J6
VCOMPLA	B8
VCOMPLB	E8
VCOMPLC	C10
VCOMPLD	E12
VCOMPLE	U11
VCOMPLF	P11
VCOMPLG	T9
VCOMPLH	P7
VPUMP	B15

FG1152	
AX2000 Function	Pin Number
NC	AP9
NC	B17
NC	B22
NC	B27
NC	B8
NC	D10
NC	D20
NC	D23
NC	D25
NC	F3
NC	F32
NC	F33
NC	F34
NC	F4
NC	G1
NC	G32
NC	G33
NC	G34
NC	H31
NC	H33
NC	J1
NC	J3
NC	J34
NC	M1
NC	M4
NC	P1
NC	P2
NC	R31
NC	T1
NC	T2
NC	V3
NC	V34
NC	W3
NC	W34
PRA	J17

FG1152	
AX2000 Function	Pin Number
PRB	F18
PRC	AD18
PRD	AH18
TCK	J9
TDI	F7
TDO	L10
TMS	H8
TRST	E6
VCCA	AA13
VCCA	AA22
VCCA	AB14
VCCA	AB15
VCCA	AB16
VCCA	AB17
VCCA	AB18
VCCA	AB19
VCCA	AB20
VCCA	AB21
VCCA	AF8
VCCA	AK28
VCCA	G30
VCCA	G5
VCCA	N14
VCCA	N15
VCCA	N16
VCCA	N17
VCCA	N18
VCCA	N19
VCCA	N20
VCCA	N21
VCCA	P13
VCCA	P22
VCCA	R13
VCCA	R22
VCCA	T13

FG1152	
AX2000 Function	Pin Number
VCCA	T22
VCCA	U13
VCCA	U22
VCCA	V13
VCCA	V22
VCCA	W13
VCCA	W22
VCCA	Y13
VCCA	Y22
VCCDA	AF26
VCCDA	AF9
VCCDA	AG17
VCCDA	AG18
VCCDA	AH14
VCCDA	AH15
VCCDA	AH17
VCCDA	AH20
VCCDA	AH21
VCCDA	AK29
VCCDA	AK6
VCCDA	E15
VCCDA	E29
VCCDA	E7
VCCDA	F15
VCCDA	F21
VCCDA	F5
VCCDA	G20
VCCDA	H17
VCCDA	H18
VCCDA	H28
VCCDA	J18
VCCDA	V27
VCCDA	V6
VCCIB0	A5
VCCIB0	B5

FG1152	
AX2000 Function	Pin Number
VCCIB0	C5
VCCIB0	D5
VCCIB0	L12
VCCIB0	L13
VCCIB0	L14
VCCIB0	M13
VCCIB0	M14
VCCIB0	M15
VCCIB0	M16
VCCIB0	M17
VCCIB1	A30
VCCIB1	B30
VCCIB1	C30
VCCIB1	D30
VCCIB1	L21
VCCIB1	L22
VCCIB1	L23
VCCIB1	M18
VCCIB1	M19
VCCIB1	M20
VCCIB1	M21
VCCIB1	M22
VCCIB2	E31
VCCIB2	E32
VCCIB2	E33
VCCIB2	E34
VCCIB2	M24
VCCIB2	N23
VCCIB2	N24
VCCIB2	P23
VCCIB2	P24
VCCIB2	R23
VCCIB2	T23
VCCIB2	U23
VCCIB3	AA23

FG1152	
AX2000 Function	Pin Number
VCCIB3	AA24
VCCIB3	AB23
VCCIB3	AB24
VCCIB3	AC24
VCCIB3	AK31
VCCIB3	AK32
VCCIB3	AK33
VCCIB3	AK34
VCCIB3	V23
VCCIB3	W23
VCCIB3	Y23
VCCIB4	AC18
VCCIB4	AC19
VCCIB4	AC20
VCCIB4	AC21
VCCIB4	AC22
VCCIB4	AD21
VCCIB4	AD22
VCCIB4	AD23
VCCIB4	AL30
VCCIB4	AM30
VCCIB4	AN30
VCCIB4	AP30
VCCIB5	AC13
VCCIB5	AC14
VCCIB5	AC15
VCCIB5	AC16
VCCIB5	AC17
VCCIB5	AD12
VCCIB5	AD13
VCCIB5	AD14
VCCIB5	AL5
VCCIB5	AM5
VCCIB5	AN5
VCCIB5	AP5

FG1152	
AX2000 Function	Pin Number
VCCIB6	AA11
VCCIB6	AA12
VCCIB6	AB11
VCCIB6	AB12
VCCIB6	AC11
VCCIB6	AK1
VCCIB6	AK2
VCCIB6	AK3
VCCIB6	AK4
VCCIB6	V12
VCCIB6	W12
VCCIB6	Y12
VCCIB7	E1
VCCIB7	E2
VCCIB7	E3
VCCIB7	E4
VCCIB7	M11
VCCIB7	N11
VCCIB7	N12
VCCIB7	P11
VCCIB7	P12
VCCIB7	R12
VCCIB7	T12
VCCIB7	U12
VCCPLA	J16
VCCPLB	K17
VCCPLC	J19
VCCPLD	L18
VCCPLE	AK19
VCCPLF	AE18
VCCPLG	AK16
VCCPLH	AF17
VCOMPLA	H16
VCOMPLB	L17
VCOMPLC	H19

PQ208	
AX250 Function	**Pin Number**
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
GND	104
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90

PQ208	
AX250 Function	**Pin Number**
GND	94
GND	99
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	52
VCCA	156
VCCA	14
VCCA	38
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	168
VCCA	195
VCCPLA	189

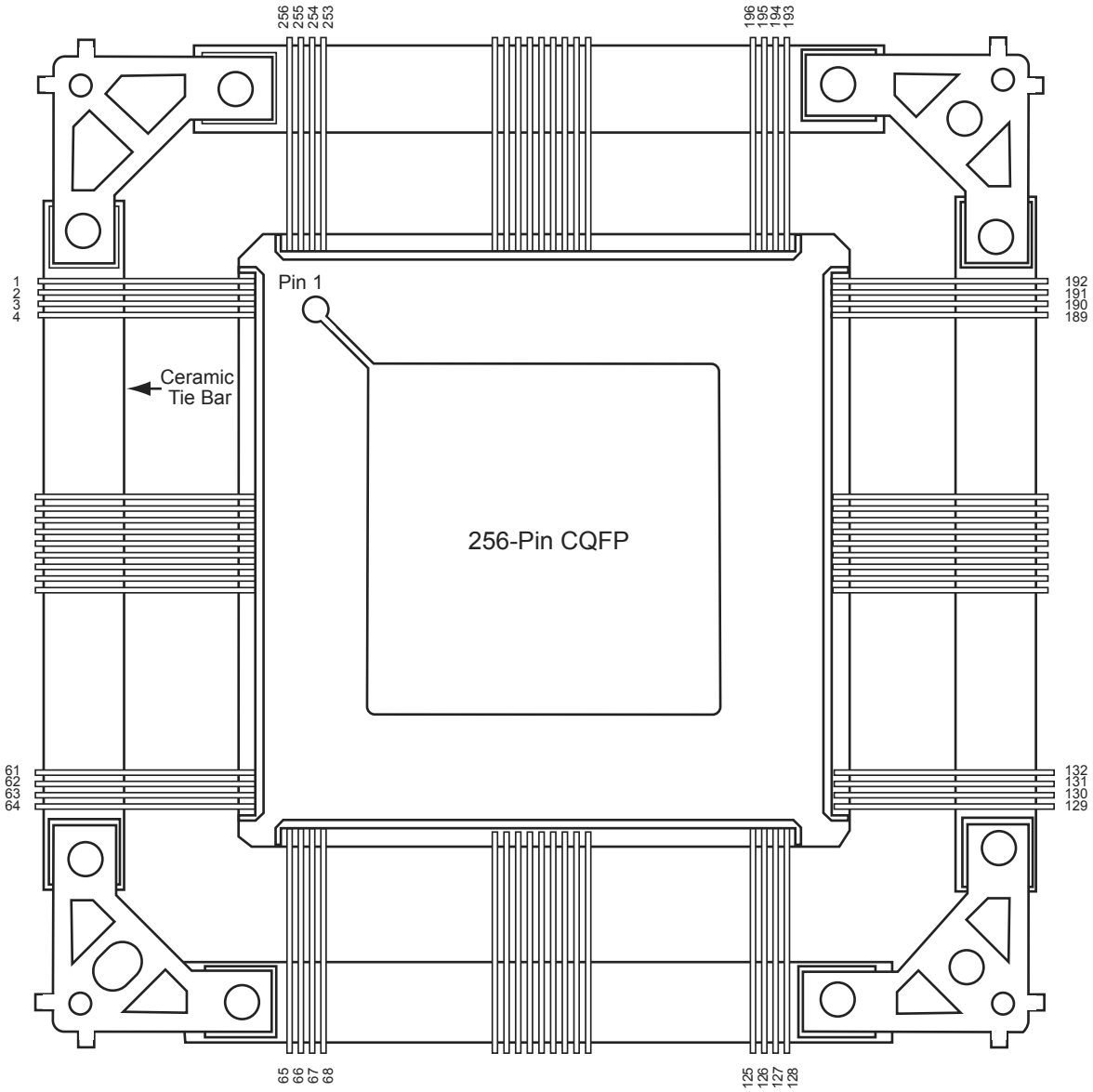
PQ208	
AX250 Function	**Pin Number**
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCCIB0	193
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

PQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

PQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

PQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CQ256



Note

For Package Manufacturing and Environmental information, visit the Resource center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

CQ352	
AX2000 Function	**Pin Number**
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX2000 Function	**Pin Number**
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

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